



LINEAR
TECHNOLOGY

APPROVALS

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ON ANGLE ± 1
2 PLACE $\pm .01$ 3 PLACE $\pm .005$
INTERPRET DIM AND TOL
PER ASME Y14.5M - 1994

TITLE: LT5560EDD, DOWNCONVERTING MIXER APPLICATION

[illegible]

Diagram illustrating the cross-section of a 4-layer PCB. The layers are labeled from top to bottom: Microstrip, Core Material, Microstrip, and Prepreg. The thicknesses are specified as follows:

- Microstrip: .0028"
- Core Material: .018"
- Microstrip: .0014"
- Prepreg: .0014"

The total thickness of the stack is .062". The diagram is labeled "4 LAYERS" and includes a circled number "9".

NOTES : Unless Otherwise Specified

1. FAB PER IPC-A-600.
2. MATERIAL: EPOXY FIBERGLASS, NEMA GRADE FR-4.
 - 2 OZ. COPPER FINISHED ON OUTER LAYERS.
 - 1 OZ. COPPER FINISHED ON INNER LAYERS.
- THICKNESS .062 +/- .006 TOTAL OF 4 LAYERS.
- FLAMABILITY RATING: 94 V-0 MINIMUM .
3. SIZE: DIMENSIONS AND TOLERANCES SHOWN.
0.00 ARE PRIMARY DATUMS.
4. DRILLING: DRILL HOLES PER SCHEDULE. PLATE THROUGH HOLES WITH COPPER, .001 INCH THICK MIN. ALL HOLE SIZES ARE SPECIFIED AFTER PLATING.
HOLE LOCATION TOLERANCES ARE +/- .003 INCH IN RELATION TO CENTER
5. FINISH: SMOBC USING LPI BOTH SIDES COLOR GREEN.

WHITE TIN IMMERSION (OMIKRON) BOTH SIDES.

6. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
7. DO NOT ALTER ARTWORK e.g. TO ADD LOGO OR DATE CODE.
8. CONTROLLED 50 OHM IMPEDANCE (AT 1 GHz FREQ.) FOR
LAYER 1-2.

- ⑨ SUBJECT TO CHANGE BY MANUFACTURER, DEPENDING ON DIELECTRIC CONSTANT DEVIATIONS. PLEASE CONSULT LTC.
10. DO NOT ALTER ARTWORK e.g. TO ADD LOGO OR DATE CODE.

FAB DRAWING